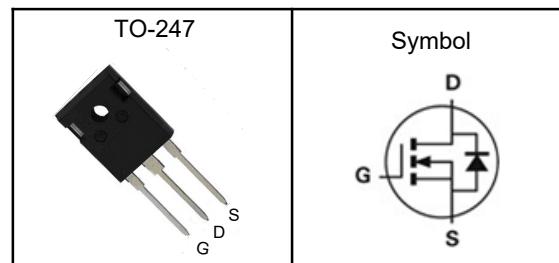


## 600V Super Junction Power MOSFET

### Features

- Low drain-source on-resistance:  $R_{DS(ON)}=0.078\Omega$ (typ)
- Easy to control gate switching
- Enhancement mode:  $V_{th} = 2.5$  to  $4.5V$
- 100% avalanche tested
- RoHS compliant

### Pin Description



### Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting.

$V_{DSS}$	600	V
$R_{DS(ON)-Typ}$	78	$m\Omega$
$I_D$	32	A

### Absolute Maximum Ratings ( $T_J=25^\circ C$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	600	V
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$E_{AS}$	Single Pulse Avalanche Energy <sup>③</sup>	199	mJ
$I_{DM}^{①}$	300 $\mu$ s Pulse Drain Current Tested	96	A
$I_D$	Continuous Drain Current	$T_c=25^\circ C$	32
$P_D$	Maximum Power Dissipation	$T_c=25^\circ C$	43
			W

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sub>1</sub> (Max)	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sub>1</sub>	2.9	$^\circ C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ C$ .

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

**600V Super Junction Power MOSFET**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)**

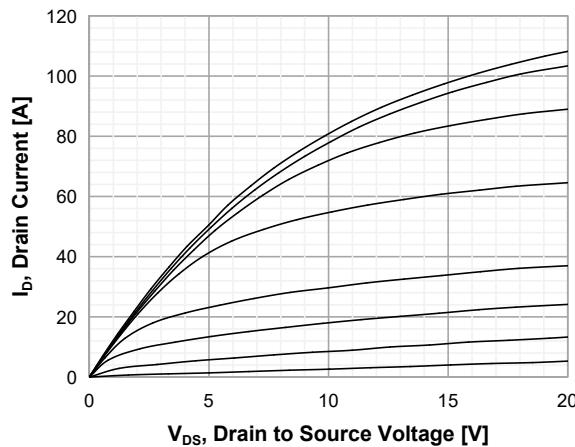
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\mu\text{A}$	600	---	---	V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=600\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$	---	---	1	$\mu\text{A}$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$ , $\text{I}_D=1.7\text{mA}$	2.5	---	4.5	V
$\text{I}_{\text{GSS}}$	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 30\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$\text{R}_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=15.3\text{A}$	---	78	90	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>⑤</sup></b>						
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{V}_{\text{DS}}=400\text{V}$ , Freq.=1MHz	---	2270	---	pF
$\text{C}_{\text{oss}}$	Output Capacitance		---	58	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	9	---	
$\text{T}_{\text{d(on)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=400\text{V}$ , $\text{R}_G=10\Omega$ , $\text{I}_D=15.3\text{A}$	---	17	---	nS
$\text{T}_r$	Turn-on Rise Time		---	10	---	
$\text{T}_{\text{d(off)}}$	Turn-off Delay Time		---	86	---	
$\text{T}_f$	Turn-off Fall Time		---	11	---	
$\text{Q}_g$	Total Gate Charge	$\text{V}_{\text{DS}}=400\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=10\text{A}$	---	52	---	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	12.7	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	22.4	---	
<b>Source-Drain Characteristics (<math>T_J=25^\circ\text{C}</math>)</b>						
$\text{V}_{\text{SD}}^{④}$	Diode Forward Voltage	$\text{I}_F=15.3\text{A}$ , $\text{V}_{\text{GS}}=0\text{V}$	---	---	1.2	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time	$\text{V}_R=400\text{V}$ , $\text{I}_F=15.3\text{A}$ , $d\text{i}/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	346	---	nS
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		---	5.1	---	nC

Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$ , duty cycle $\leq 2\%$ ).

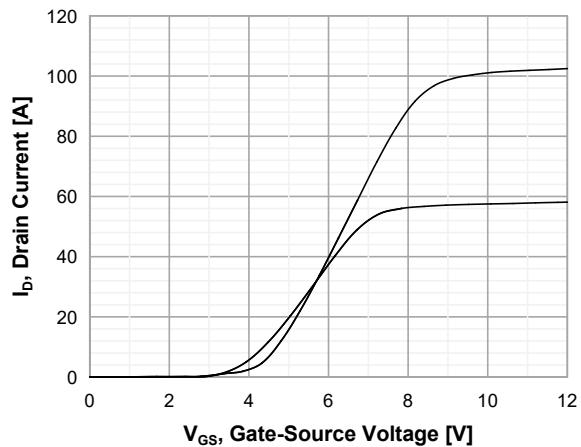
Note ⑤ : Guaranteed by design, not subject to production testing.

## 600V Super Junction Power MOSFET

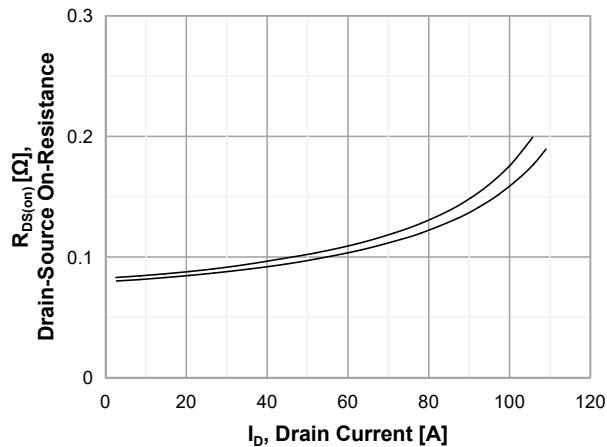
Hnd]WU 7\ UFUWYf]ghWg



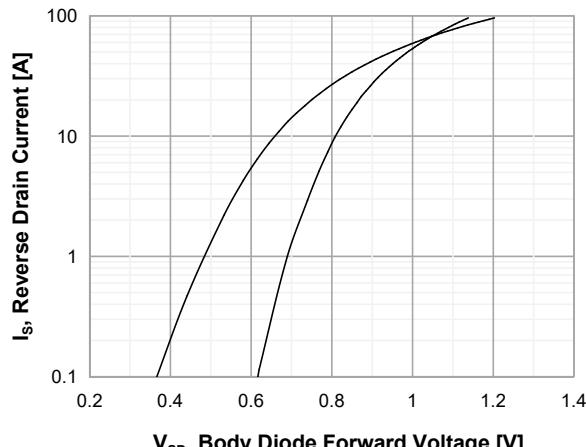
**Figure 1. On-Region Characteristics**



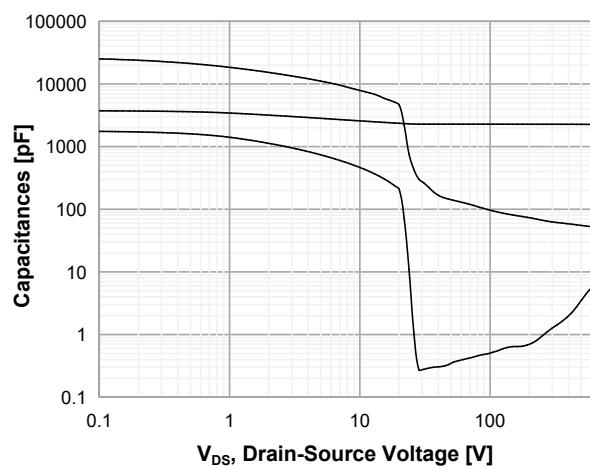
**Figure 2. Transfer Characteristics**



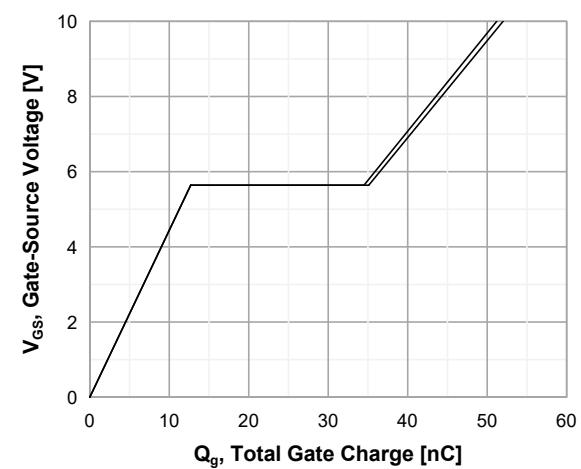
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

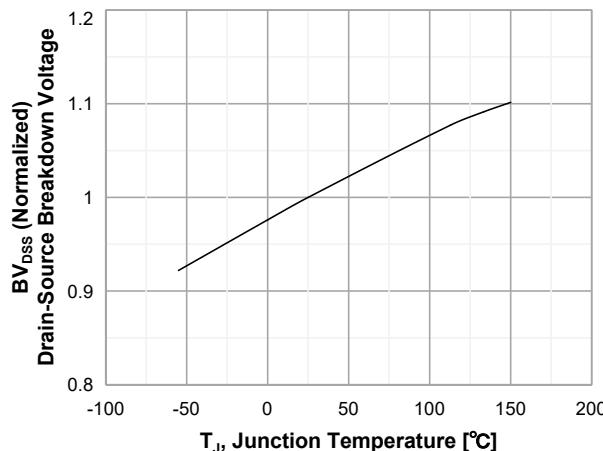


**Figure 5. Capacitance Characteristics**

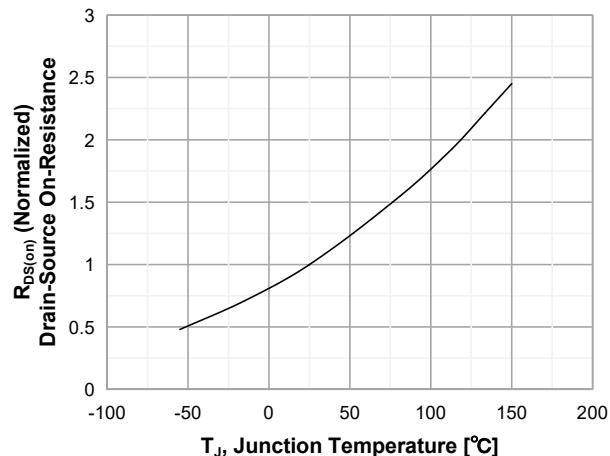


**Figure 6. Gate Charge Characteristics**

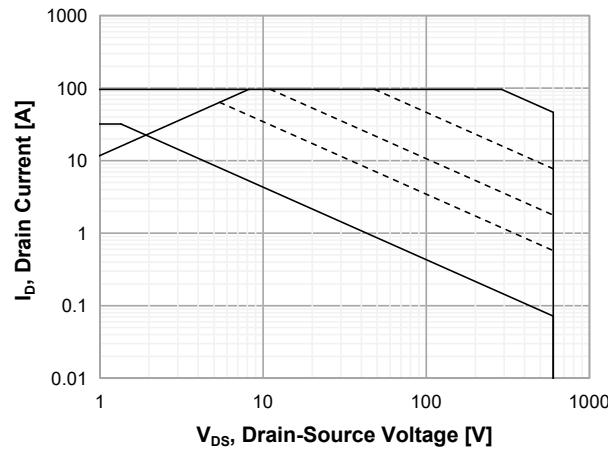
## 600V Super Junction Power MOSFET



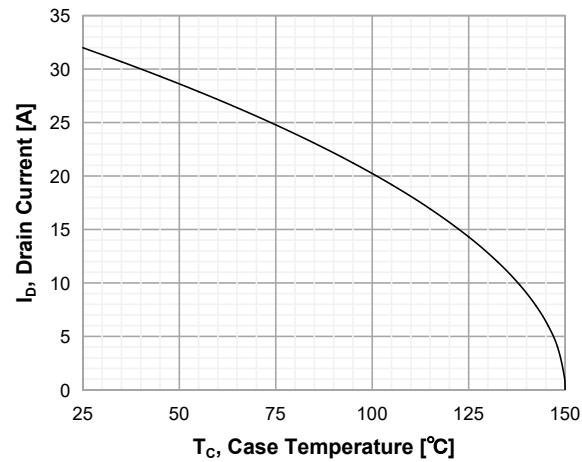
**Figure 7. Breakdown Voltage Variation  
vs Temperature**



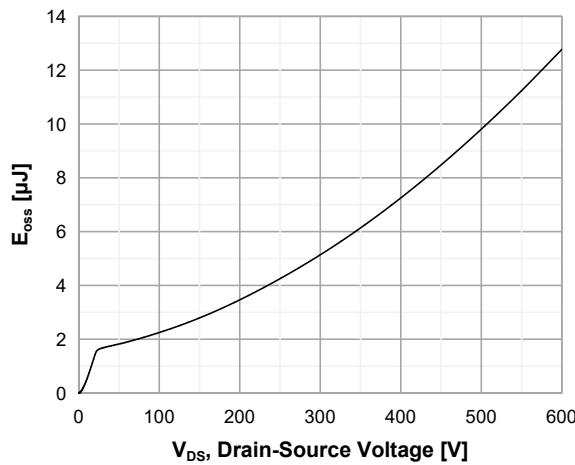
**Figure 8. On-Resistance Variation  
vs Temperature**



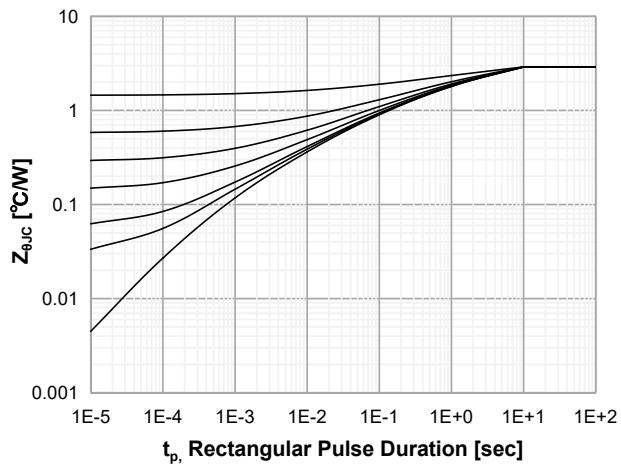
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs.  
Case Temperature**



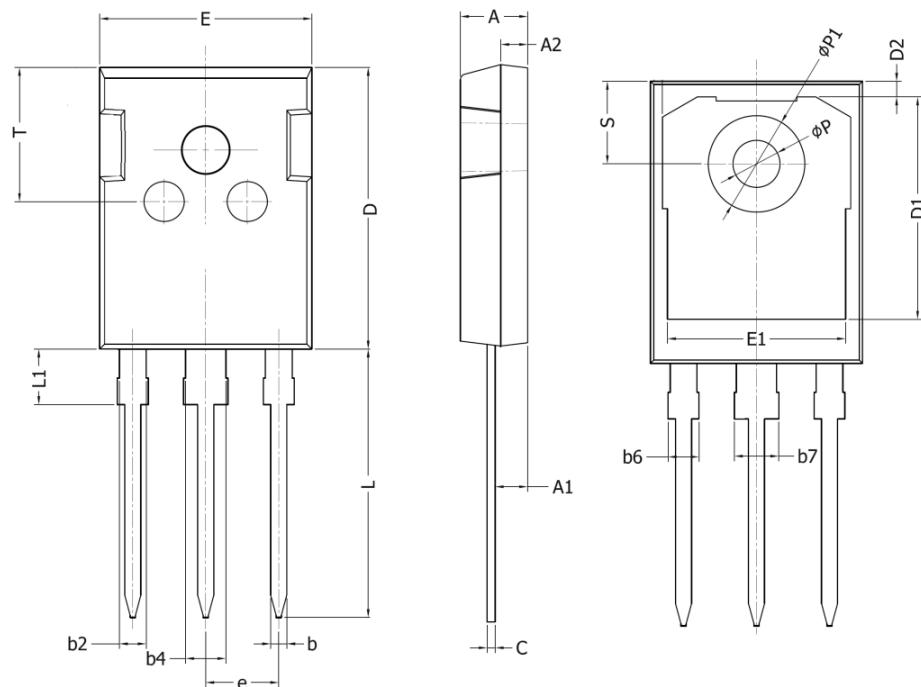
**Figure 11.E<sub>oss</sub> vs. Drain to Source Voltage**



**Figure 12.Transient Thermal Response Curve**

## 600V Super Junction Power MOSFET

### TO-247 Package Outline Dimensions



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.90	5.20
A1	2.31	2.51
A2	1.9	2.1
b	1.16	1.26
b2	1.96	2.06
b4	2.96	3.06
b6	-	2.25
b7	-	3.25
C	0.59	0.66
D	20.90	21.20
D1	16.25	16.85
D2	1.05	1.35
E	15.75	16.10
E1	13.00	13.60
e	5.436 BSC	
L	19.80	20.20
L1	-	4.30
P	3.40	3.60
P1	7.00	7.40
S	6.05	6.25
T	9.80	10.20